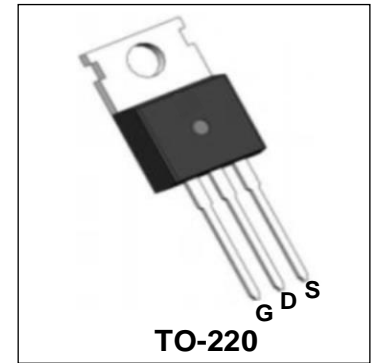


100V N-Channel Enhancement Mode Power MOSFET

Description

WMK099N10LG2 uses Wayon's 2nd generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.

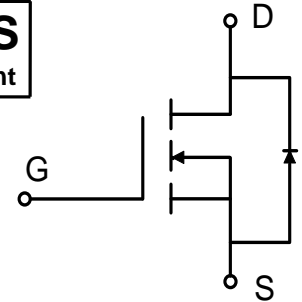


Features

- $V_{DS} = 100V$, $I_D = 65A$ (Silicon Limited)
 $R_{DS(on)} < 9.9m\Omega @ V_{GS} = 10V$
 $R_{DS(on)} < 13m\Omega @ V_{GS} = 4.5V$
- Low Gate Charge
- High Speed Power Switching
- 100% EAS Guaranteed

Applications

- Hard Switching and High Speed Circuit
- DC/DC Conversion
- Synchronous Rectification in SMPS



Absolute Maximum Ratings

| Parameter | | Symbol | Value | Unit |
|---|---------------------|----------------|------------|------------|
| Drain-Source voltage | | V_{DS} | 100 | V |
| Gate-Source voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current ¹ (Silicon Limited) | $T_C = 25^\circ C$ | I_D | 65 | A |
| | $T_C = 100^\circ C$ | | 45 | |
| Pulsed Drain Current ² | | I_{DM} | 180 | A |
| Single Pulse Avalanche Energy ³ | | EAS | 80 | mJ |
| Avalanche Current | | I_{AS} | 40 | A |
| Total Power Dissipation ⁴ | $T_C = 25^\circ C$ | P_D | 96 | W |
| Operating Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|--------------|
| Thermal Resistance from Junction-to-Ambient ¹ | $R_{\theta JA}$ | 49 | $^\circ C/W$ |
| Thermal Resistance from Junction-to-Case ¹ | $R_{\theta JC}$ | 1.3 | $^\circ C/W$ |

Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--|-------------------------|---|------|------|-----------|------------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 100 | - | - | V |
| Gate-body Leakage current | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 20V$ | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | $T_J=25^\circ\text{C}$ | $V_{DS} = 100V, V_{GS} = 0V$ | - | - | 1 | μA |
| | $T_J=100^\circ\text{C}$ | | - | - | 100 | |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1.3 | 1.85 | 2.5 | V |
| Drain-Source On-Resistance ² | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 20A$ | - | 8.5 | 9.9 | m Ω |
| | | $V_{GS} = 4.5V, I_D = 20A$ | - | 11.2 | 13 | |
| Forward Transconductance ² | g_{fs} | $V_{DS} = 5V, I_D = 10A$ | - | 80 | - | S |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 50V, V_{GS} = 0V, f = 1\text{MHz}$ | - | 1620 | - | μF |
| Output Capacitance | C_{oss} | | - | 300 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 5.5 | - | |
| Switching Characteristics | | | | | | |
| Gate Resistance | R_g | $V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$ | - | 1.1 | - | Ω |
| Total Gate Charge | Q_g | $V_{GS} = 4.5V, V_{DS} = 50V, I_D = 20A$ | - | 11.6 | - | nC |
| Total Gate Charge | Q_g | $V_{GS} = 10V, V_{DS} = 50V, I_D = 20A$ | - | 23 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 3.8 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 6.3 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{GS} = 10V, V_{DS} = 50V, R_G = 10\Omega, I_D = 20A$ | - | 5.9 | - | nS |
| Rise Time | t_r | | - | 3.9 | - | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 17 | - | |
| Fall Time | t_f | | - | 2.9 | - | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Diode Forward Voltage ² | V_{SD} | $I_S = 20A, V_{GS} = 0V$ | - | - | 1.2 | V |
| Continuous Source Current ^{1,5} | I_S | $V_G = V_D = 0V, \text{Force Current}$ | - | - | 65 | A |
| Body Diode Reverse Recovery Time | t_{rr} | $V_R = 50V, I_F = 20A, di/dt = 500A/\mu s$ | - | 42 | - | nS |
| Body Diode Reverse Recovery Charge | Q_{rr} | | - | 155 | - | nC |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is $V_{DD} = 25V, V_{GS} = 10V, L = 0.1\text{mH}, I_{AS} = 40A$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation

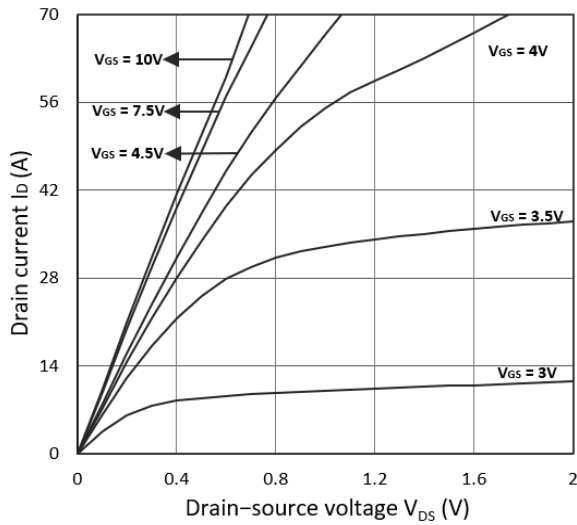


Figure 1. Output Characteristics

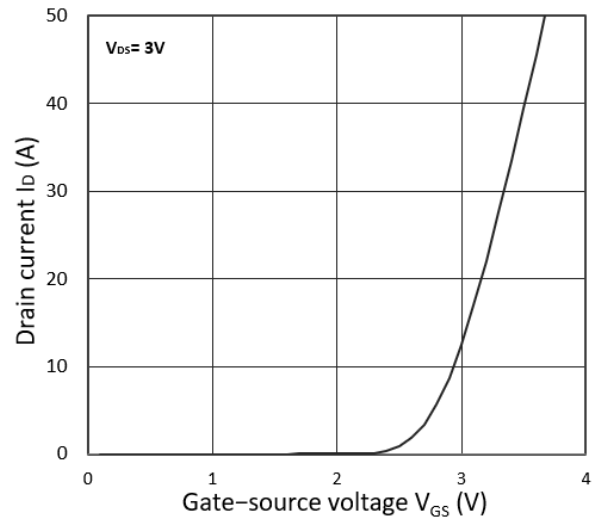


Figure 2. Transfer Characteristics

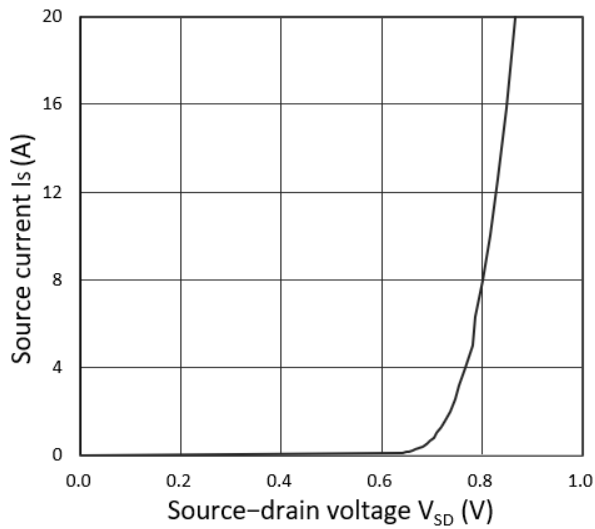


Figure 3. Forward Characteristics of Reverse

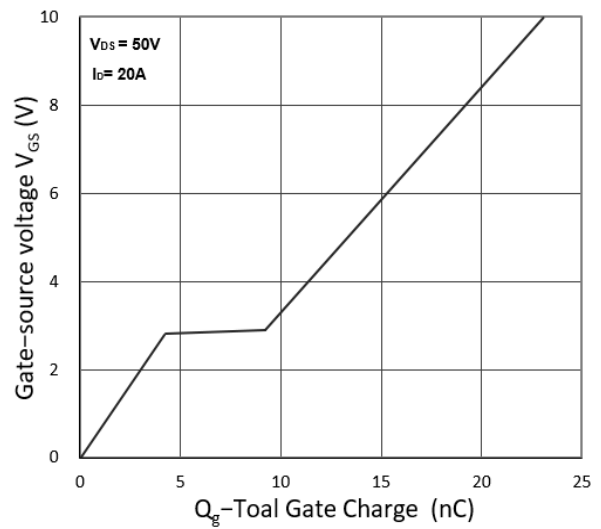


Figure 4. Gate Charge Characteristics

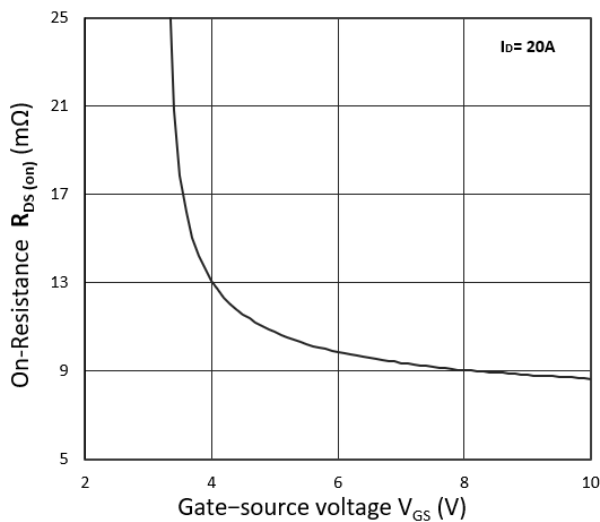


Figure 5. $R_{DS(ON)}$ vs. V_{GS}

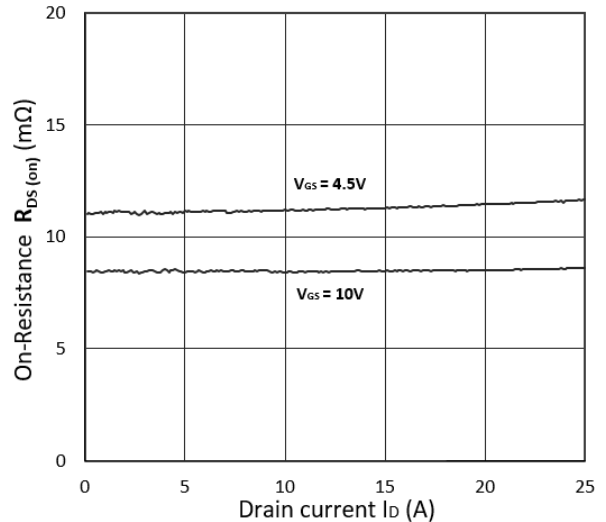


Figure 6. $R_{DS(ON)}$ vs. I_D

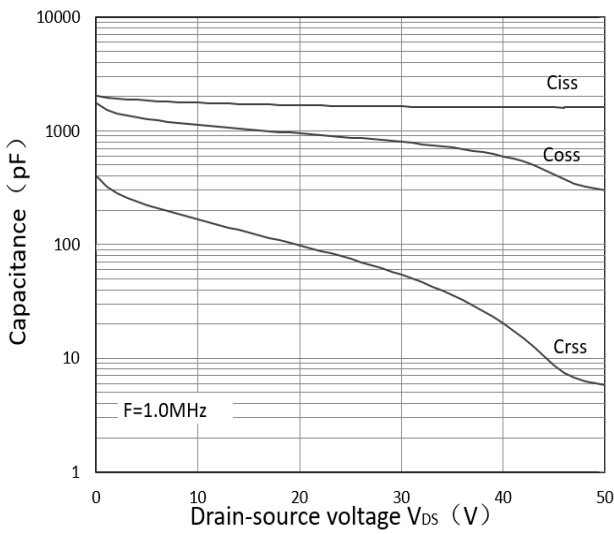


Figure 7. Capacitance Characteristics

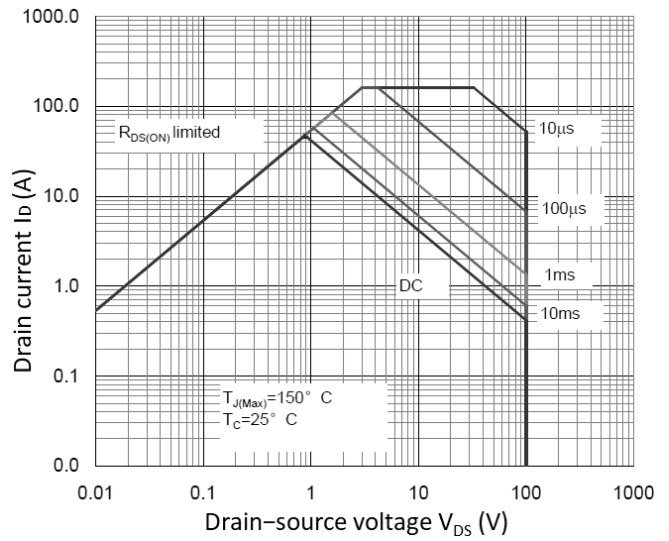


Figure 8. Safe Operating Area

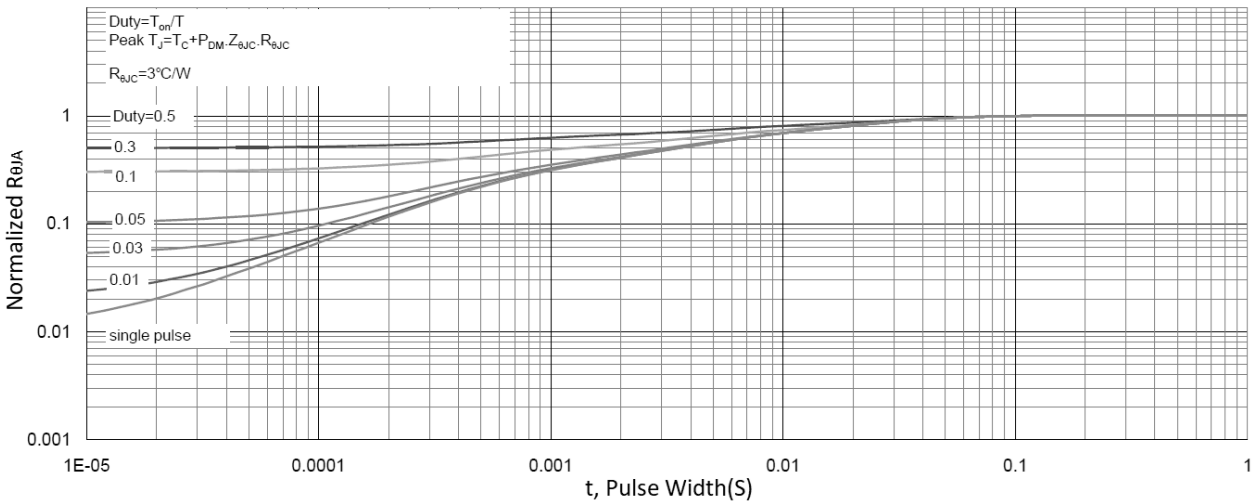


Figure 9. Normalized Maximum Transient Thermal Impedance

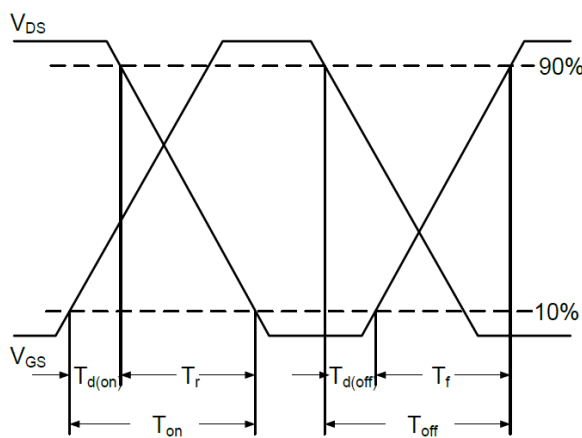


Figure 10. Switching Time Waveform

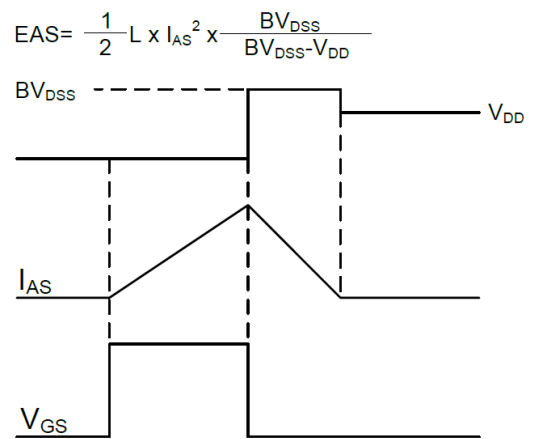
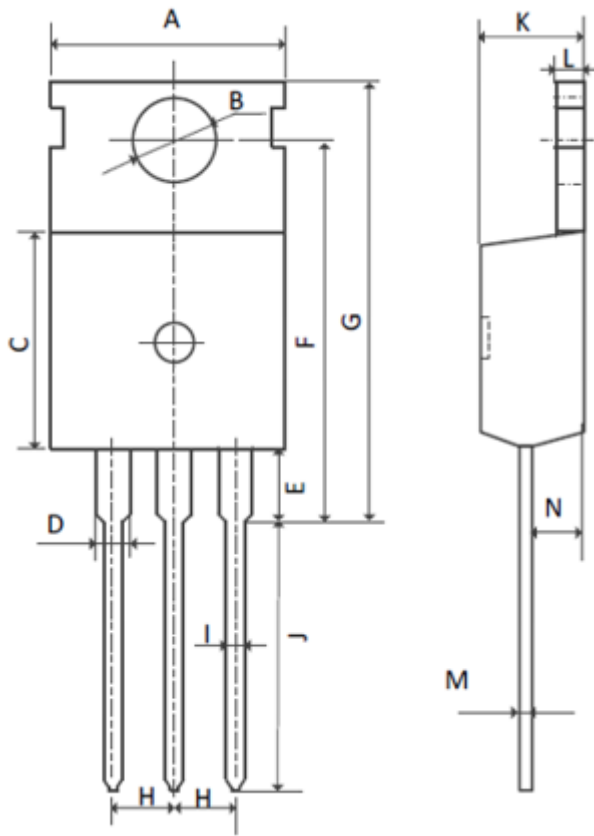


Figure 11. Unclamped Inductive Switching Waveform

Mechanical Dimensions for TO-220

COMMON DIMENSIONS

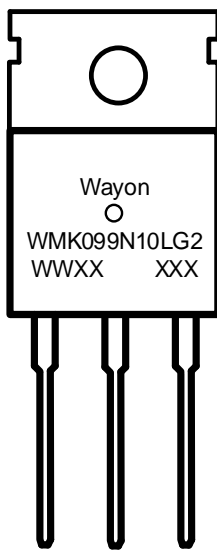


| SYMBOL | MM | |
|--------|----------|-------|
| | MIN | MAX |
| A | 9.70 | 10.30 |
| B | 3.40 | 3.80 |
| C | 8.80 | 9.40 |
| D | 1.17 | 1.47 |
| E | 2.60 | 3.40 |
| F | 15.10 | 16.70 |
| G | 19.55MAX | |
| H | 2.54REF | |
| I | 0.70 | 0.95 |
| J | 9.35 | 11.00 |
| K | 4.30 | 4.77 |
| L | 1.20 | 1.45 |
| M | 0.40 | 0.65 |
| N | 2.20 | 2.60 |

Ordering Information

| Part | Package | Marking | Packing method |
|--------------|---------|--------------|----------------|
| WMK099N10LG2 | TO-220 | WMK099N10LG2 | Tube |

Marking Information



WMK099N10LG2 = Device code
 WWXX XXX= Date code


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